

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Bruce et al.

Examiner:

Mohamed, C.

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Group Art Unit:

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Title:

RESISTIVITY ANALYSIS

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence and the papers, as described hereinabove, are being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on February 7, 2003.

By: L-m. Nichols

## **OFFICE ACTION RESPONSE AND AMENDMENT**

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated November 18, 2002, please consider the following amendment and remarks.

## In the Drawings

Enclosed please find a replacement drawing sheet for Fig. 1 including labels for each box, in red ink.

## In the Claims

G1 73:1E0:

Please replace claims 1, 4 and 21 as indicated below. The changes may be found on the attached sheet.

(Amended) A method for analyzing a semiconductor die having suspect circuitry that includes a multitude of circuit paths, the method comprising:

while using a state-changing operation of the suspect circuitry to cause a failure due to the suspect circuitry, identifying one of the circuit paths that electrically changes in response to heat and detecting that a particular circuit portion therein is resistive.

30